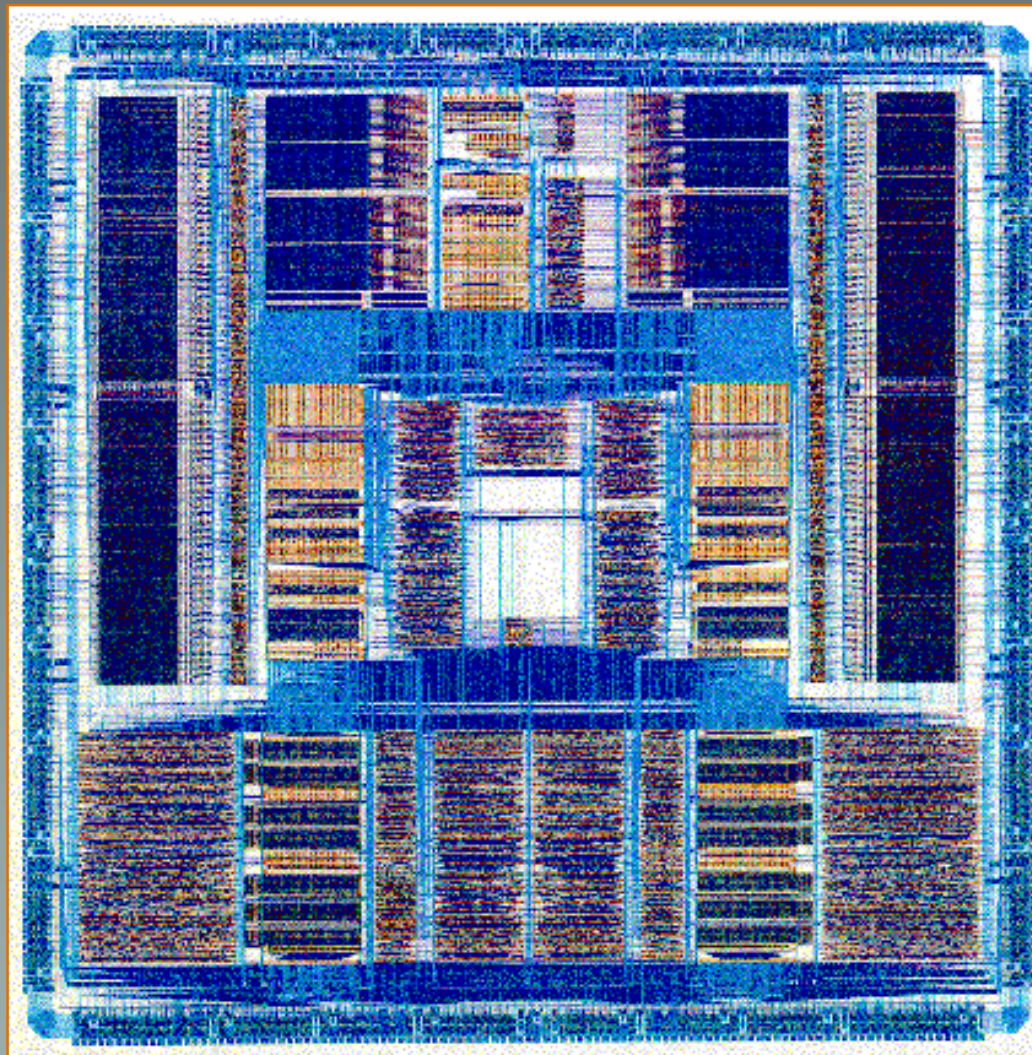


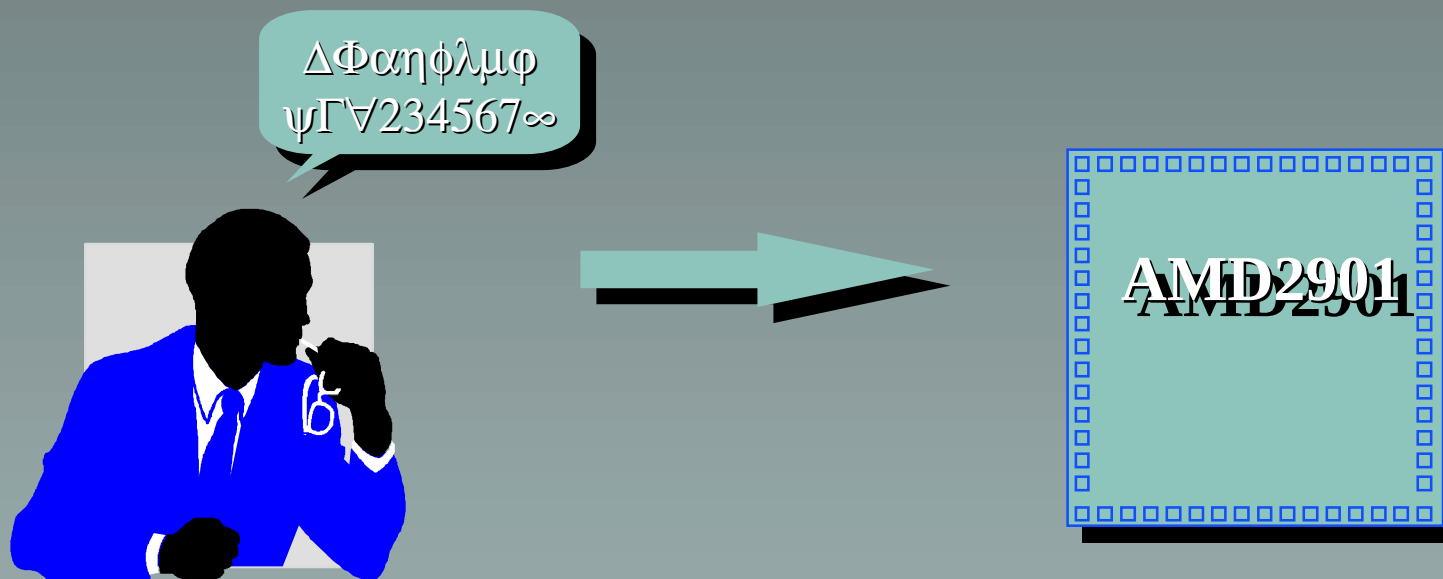
OUTLINE

I - INTRODUCTION

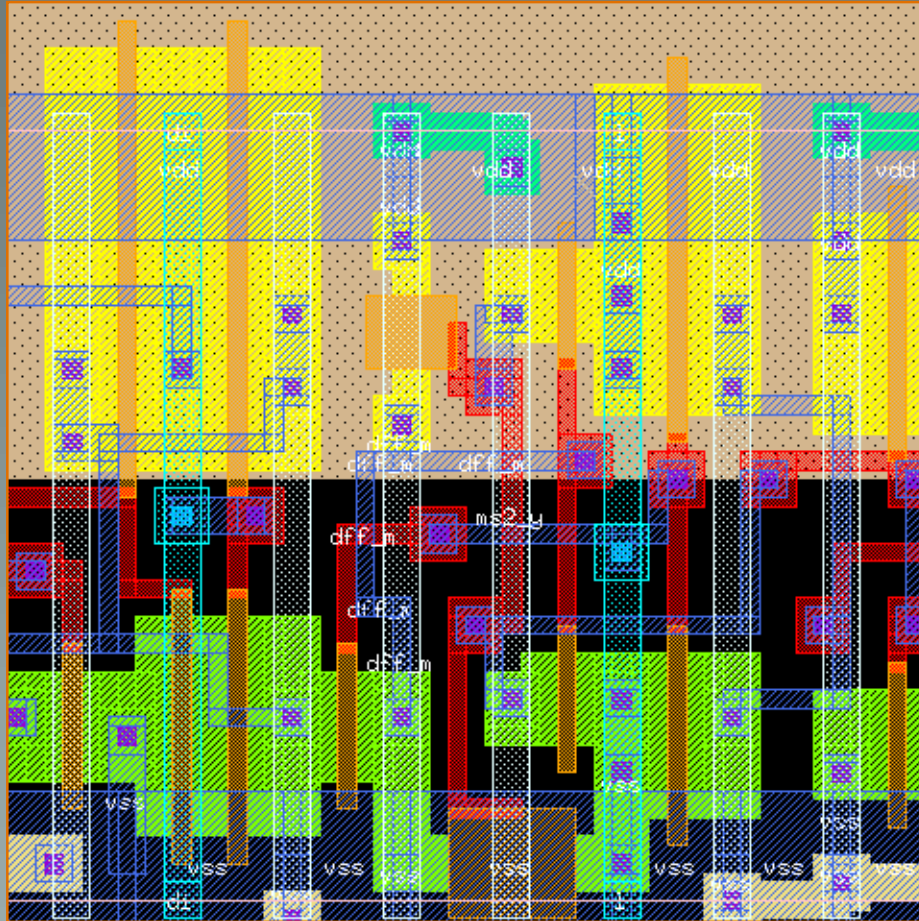
II - DESIGN METHODOLOGY : AN OVERVIEW



DESIGNER'S DREAM

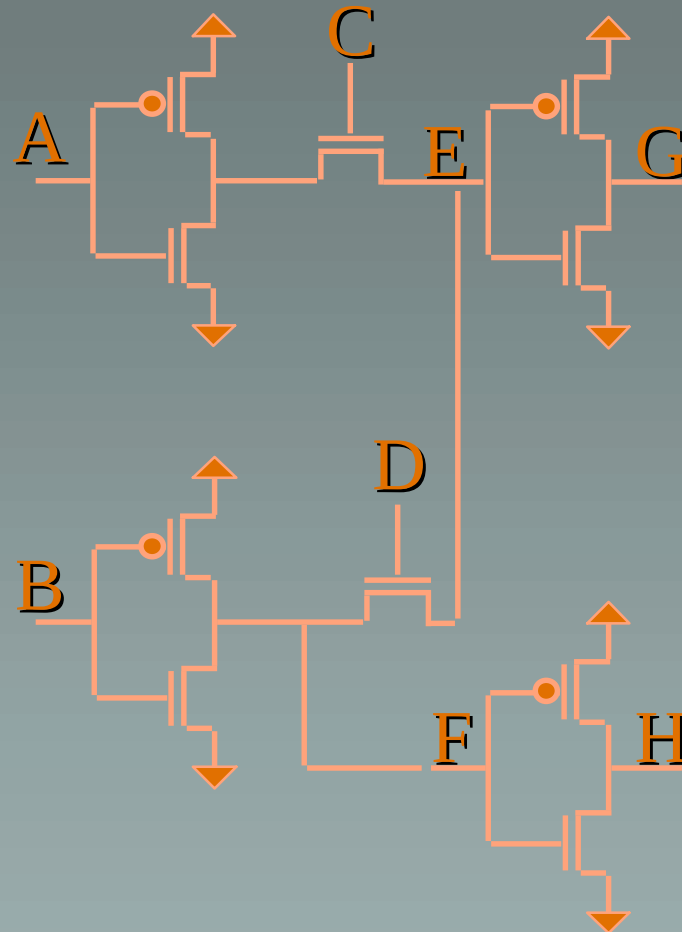


Millions of Segments Put Together



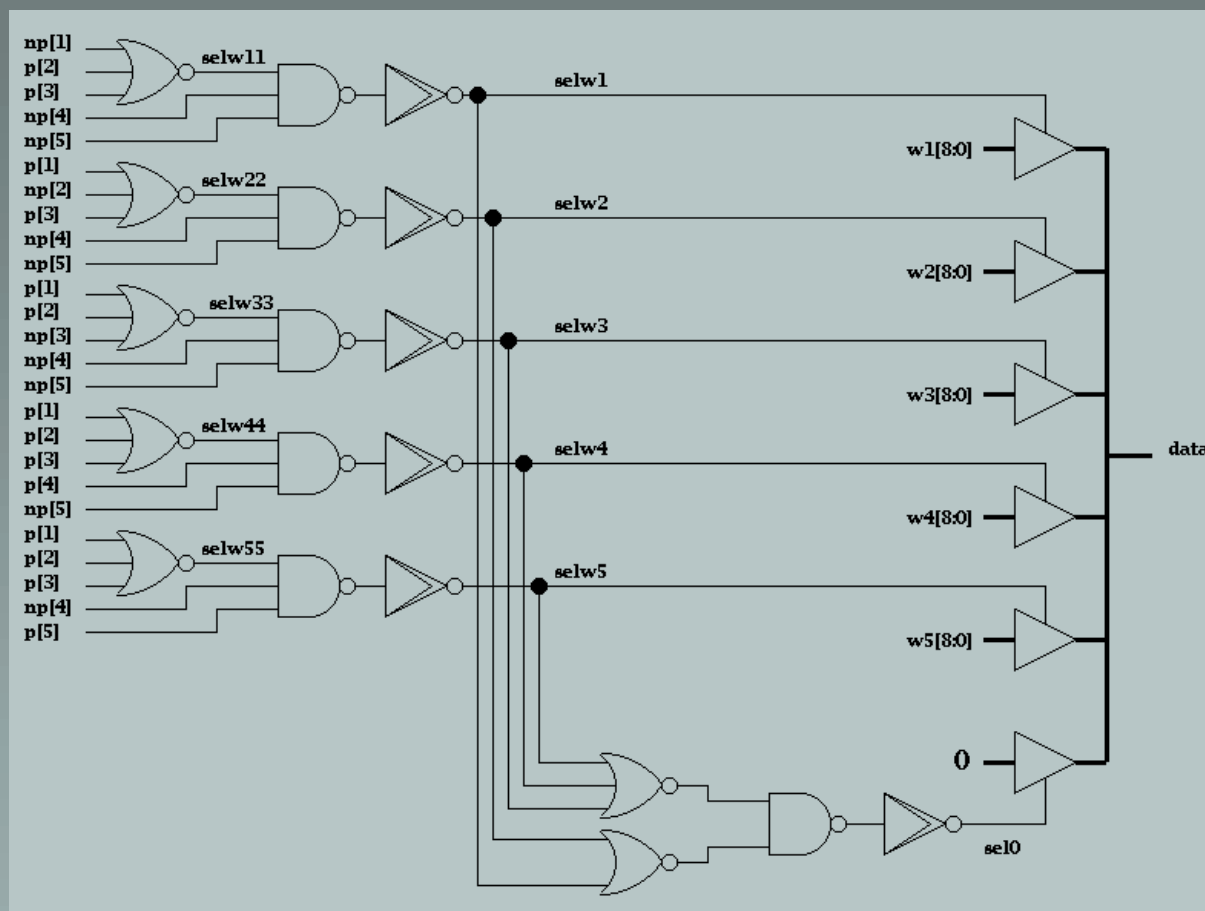
How to deal with such complexity ?

Millions of Transistors Connected Together



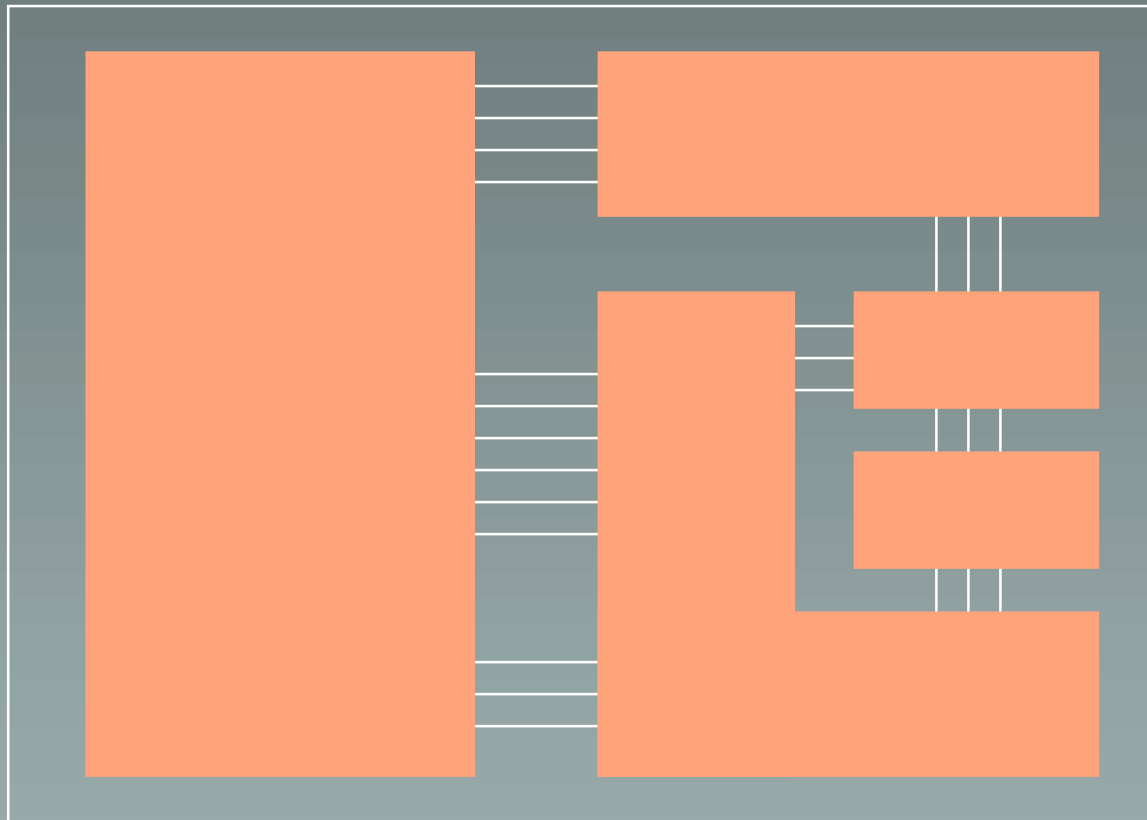
✗ Still Too Complex.....!!!

Thousands of Cells Connected Together



✗ Still Too Complex....!!!

Dozen of Functional Blocks Communicating Together



☹ I'm Starting to Understand

A Set of Equations Reflecting the Circuit's functionality

entity simple is

port (

a, b: Bit;

c, d : bit

);

architecture simple is

a <= b or c

d <= b and c;

end;

✓ I Understand What this Circuit is Supposed to Do

so,

How to deal with such complexity ?

✓ ABSTRACTION

✓ HIERARCHY

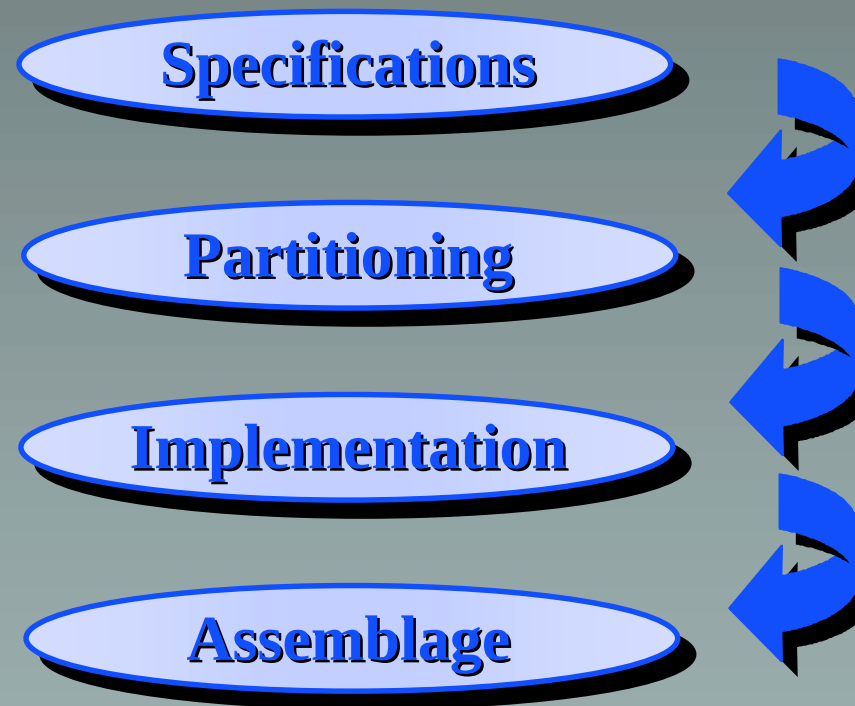
LEVELS OF ABSTRACTION

To Go Across These Different Levels of Abstraction
I Need

A Design M E T H O D O L O G Y

DESIGN METHODOLOGY

TOP-DOWN METHODOLOGY



STEP 1: SPECIFICATIONS (1)

Put Down the Circuit Concept

Two reasons:

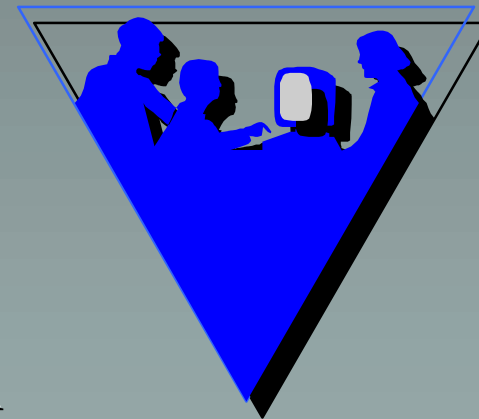
- To be able to check it before manufacturing
- To have a reference manual for communication

STEP 1: SPECIFICATIONS (2)

Communication Language

Between People on the Project
Between People and Computers

- No Ordinary Language
- Accurate Language
- A Language that Can Be Simulated



STEP 2: PARTITIONING (1)

Divide and conquer strategy

Very difficult step: Relays on the **know-how** of the designer.

Main idea: To **split** into several small parts

HIERARCHY

STEP 2: PARTITIONING (2)

The cutting is guided by:

1 – REGULARITY OR NOT

- ✓ Identify regular blocks
- ✓ Identify random logic blocks

STEP 2: PARTITIONING (3)

The cutting is guided by:

2 – TIMING ASPECTS

- ✓ Coarse Estimation of Timing
- ✓ Looking for a Good Balance

STEP 2: PARTITIONING (4)

The cutting is guided by:

3 – TOPOLOGY

- ✓ Already in mind the circuit form
- ✓ An idea about the size of each part
 - ✓ An idea about the routing
- ✓ Optimizing silicon area usage

STEP 2: PARTITIONING (5)

The cutting is guided by:

4 – TECHNOLOGY

- ✓ Using GAAS or CMOS ?
- ✓ Using PALs or Standard Cells ?

STEP 2: PARTITIONING (6)

The cutting is guided by:

5 – CAD TOOLS

- ✓ What tools do I have to make my circuit ?

STEP 3: IMPLEMENTATION

EACH PART WILL BE IMPLEMENTED USING A PARTICULAR METHOD. WHEN I SPLIT MY CIRCUIT, I ALREADY HAVE DECIDED WHICH ONE

STEP 4: ASSEMBLAGE

THE ASSEMBLAGE IS DONE IN A HIERARCHICAL
WAY, STARTING FROM THE LOWEST LEVEL

CONCLUSION (1)

At each step, the information is enhanced:

1. From the idea down to the specifications
2. When structuring the model in an other way
3.

➡ At each step, a verification is to be done

CONCLUSION (2)

All along the methodology, we handled different views:

1 – EQUATIONS

2 – NETLISTS

3 – LAYOUT

CONCLUSION (3)

THERE IS A
METHOD

